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REMARKS

The application has been carefully reviewed in light of the Office Action dated May 9, 2006. Claims 1 to 3 and 5 to 20 are in the application, with Claims 1 and 17 being independent. Claim 4 has been cancelled without prejudice. Claims 1 and 17 have been amended herein. Reconsideration and further examination are respectfully requested.

Claims 1, 2, 11, 19, and 20 were rejected under 35 U.S.C. § 102(b) over U.S. Patent No. 5,625,199 (Baumbach). Claims 3 to 6 were rejected under 35 U.S.C. § 103(a) over Baumbach. Claims 12, 17, and 18 were rejected under 35 U.S.C. § 103(a) over Baumbach in view of Shi. Claim 13 was rejected under 35 U.S.C. § 103(a) over Baumbach in view of Japan 2001-94107 (JP '107). Claims 1, 2, 7 to 10, and 14 were rejected under 35 U.S.C. § 103(a) over the Jackson article (Jackson) in view of the Parikh article (Parikh). Claims 15 and 16 were rejected under 35 U.S.C. § 103(a) over Jackson and Parikh, and further in view of U.S. Patent No. 6,326,640 (Shi). These rejections are respectfully traversed.

Claim 1 recites, *inter alia*, (a) the island-shaped protrusion layer is formed by spin-coating or spray-coating, in combination with (b) the organic semiconductor layer is in contact with the island-shaped protrusions. Claim 17 recites, *inter alia*, (a) the island-shaped protrusions are formed in a dispersed manner by spin-coating or spray-coating, in combination with (b) the organic semiconductor layer is formed in contact with the island-shaped protrusions.

Applicant respectfully submits that none of Baumbach, Jackson, Parikh, and Shi discloses or suggests at least the above-discussed combinations of features.

The Office Action takes the position that Baumbach's organic active layer (58) and patterned isolation layer (54) correspond, respectively, to the organic semiconductor layer and the island-shaped protrusions of the present invention. However, as shown in Figure 9 of Baumbach, organic active layer (58) is not in contact with items (54).

With respect to Jackson and Parikh, Applicant respectfully submits that the octadecyltrichlorosilane (OTS) treatments described in these documents cannot be carried out by spin coating or spray coating.

Nothing in Shi is seen to remedy the deficiencies of Baumbach, Jackson, and Parikh.


It is further respectfully submitted that there has been no showing of any indication of motivation in any of the cited documents that would lead one skilled in the art to arrive at the above-discussed combinations of features recited by Claims 1 and 17.

The dependent claims are also submitted to be patentable because they set forth additional aspects of the present invention and are dependent from the independent claims discussed above. Therefore, separate and individual consideration of each dependent claim is respectfully requested.

The application is believed to be in condition for allowance, and a Notice of Allowance is respectfully requested.

Applicant's undersigned attorney may be reached in our Costa Mesa, California office by telephone at (714) 540-8700. All correspondence should be directed to our address given below.

Respectfully submitted,



Damond E. Vadnais
Attorney for Applicant
Registration No. 52,310

FITZPATRICK, CELLA, HARPER & SCINTO
30 Rockefeller Plaza
New York, New York 10112-3800
Facsimile: (212) 218-2200

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